

TGP2000E Thermal Gap Filler Pad

BENEFITS AND FEATURES

- High thermal performance
- Ultra-high compressibility for low stress applications
- Excellent surface wetting for low contact resistance
- Electrically insulating
- Naturally tacky for application

OVERVIEW

Honeywell TGP2000E Thermal Gap Filler Pads provide high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing. TGP2000E naturally tacky, and require no additional adhesive which could inhibit thermal performance. Products are available in thickness range from 0.5mm to 5.0mm.

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductor logics & memory

STORAGE & USE

- Shelf life 12 months at 0-35°C,
≤65% RH

Property	TGP2000E	Test Method
Color	Red	Visual
Thickness (mm) 1*	0.5-5.0	ASTM D374
Density(g/cm ³)	2.3	ASTM D792
Hardness (Shore00)	50	ASTM D2240
Thermal Conductivity (W/m·K)	2.0	ASTM D5470
Thermal Impedance (°C·in ² /W) (1mm@10psi, Typical Value)	0.95	ASTM D5470
Dielectric Constant@1MHz	5.5	ASTM D150
Volume Resistivity (ohm-cm)	1.0 x 10 ¹⁴	ASTM D257
Volatile Content (TML%)	0.35	HON Internal
Volatile Content (CVCm%)	0.05	HON Internal
Flammability Rating	V-0	UL 94
Operating Temperature (°C)	-40~150	HON Internal

1* Thickness range: 0.5-5.0mm with 0.25mm incremental

Thickness Tolerance: ≥1.0mm, ±10%

0.5-1.0mm, ±0.1mm

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102

China: 400-840-2233

Germany: 49-5137-999-9199

Japan: 81-3-6730-7092

Korea: 82-2-3483-5076

Singapore: 65-6580-3593

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